LEX COMPUTECH

博來科技股份有限公司

Lex SYSTEM®

2026 V01

About LEX

Name	**LEX Computech CO.,LTD**		
Established	May 15th,1990	Stock Exchange	TPEx 7562
Capital	USD 7.15 million in 2025	Business Items	Industrial Motherboards, Embedded Systems, AI Image Analysis, Smart Cities, Smart Manufacturing, Intelligent Healthcare, Fanless Rugged Panel PC, Smart Transportation ,Edge Computing and Expansion Module Products
Employees	227 (R&D / 31)		
Worldwide Support	Headquarters： Taiwan (104) Subsidiary： Netherlands (11), TD Computech (112) Sales Representatives : South Korea		

Design and Manufacture in Taiwan

Established in 1990, LEX Computech (TPEx:7562), is a Taiwan-based industrial computer developer and manufacturer with ISO 9001 certification. Headquartered in New Taipei City, it operates R&D, management, sales, and manufacturing units, with additional sales channels in Europe and Asia. LEX Computech ’s products hold various patents and certifications for automotive and railway safety and include customized OEM/ODM solutions for industrial computing. It is also a member of the Intel IoT Solutions Alliance.

Company Milestones

1990

Founded in Taipei, specialized in designing & manufacturing computer graphics cards.

1993

Established Europe Sales Hub, selling 'Mentor' brand computer peripherals

2002

Established IPC R&D Division, set up European sales headquarters in the Netherlands.

2004

ISO 9001 & 14001 certified.

2011

COMPUTEX TAIPEI D&I awards

2012

iF design awards
red dot design awards
Certified HDMI Adopter

2013

Intel® Internet of Things Solutions Alliance Member

2016

Built PCB SMT/DIP Production line
Via TD Computech-
Professional MES Manufacturer

2021

Intel® Partner Titanium member

2022

Founding Member of ICAA" (Intelligent Computing & IoT Association)

2023

Successfully registered on Emerging Stock Board : 7562

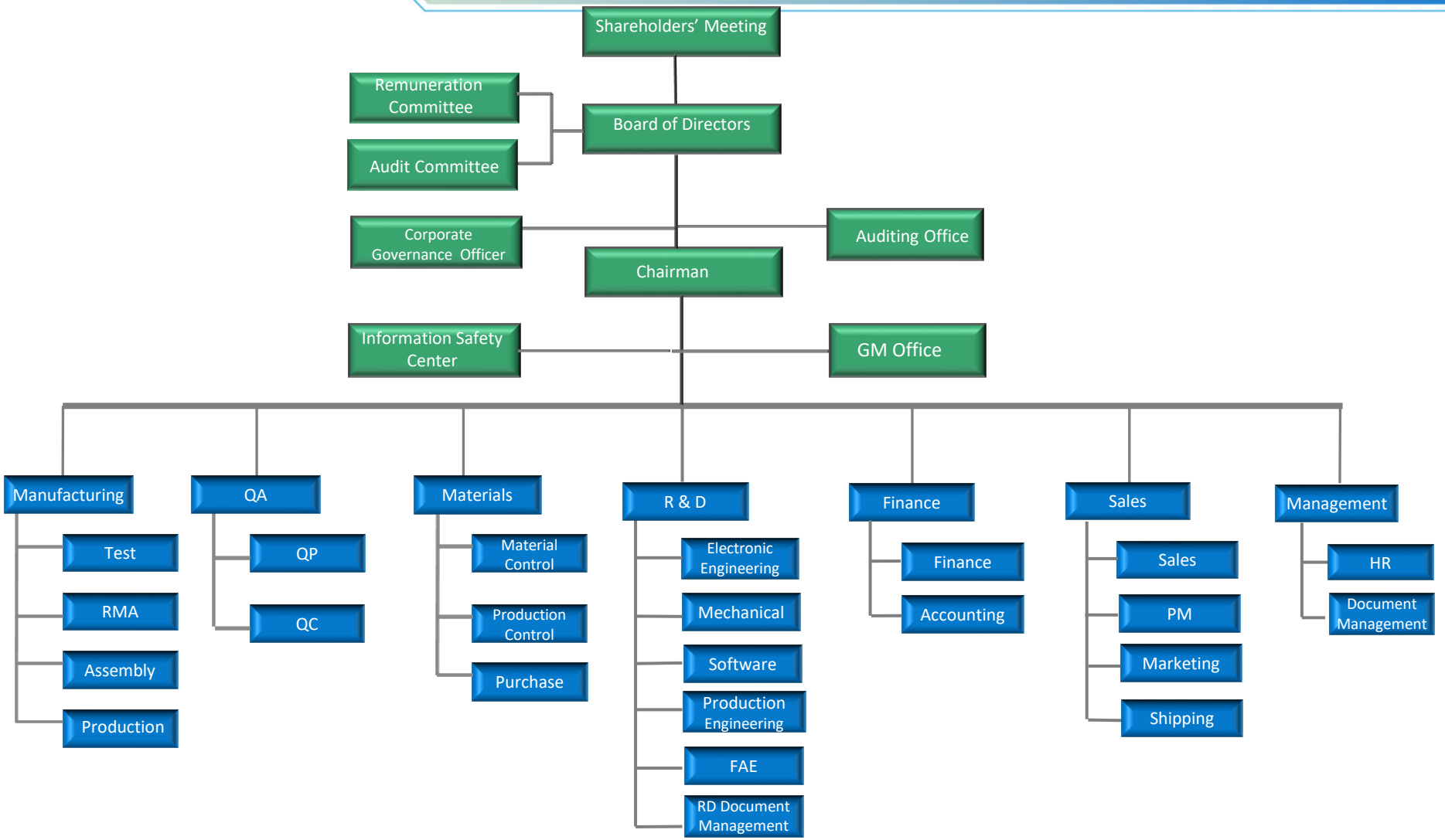
2024

Compliant with ISO 14064-1 : 2018

2025

ISO/IEC 27001 certified.

Organization Chart

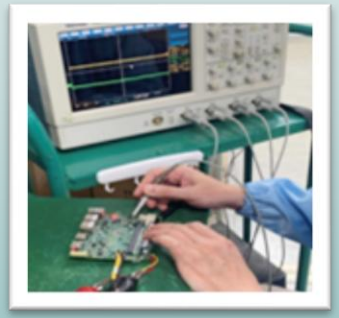


Striving for Excellence

Product Stability and Reliability

LEX SYSTEM holds complete ISO certification, dedicated to delivering high-quality products that meet international standards. With comprehensive quality management from design to production, we provide highly stable and durable products, ensuring exceptional customer satisfaction

- Digital Oscilloscope



- Programmable Aging Constant Temperature and Humidity Test Chamber

- Waterproof and Airtight Testing Machine

- Burn-in Chamber

- Vibration Testing Machine

Certification:

ISO 27001 · ISO9001 · ISO14001 · UL · EN50155 · CCC · E13 · EAC · CE · FC · VCI · ROHS

MES - Manufacturing Execution System

Professional Motherboard Manufacturing Process

Implementing traceability of production materials and production process through MES could :

- Meet enterprise needs in product management, quality control, equipment integration, problem traceability analysis, and real-time data collection.
- Leverage MES advantages for precise task execution and providing real-time production data access to customers.

SMT

Surface Mount Technology

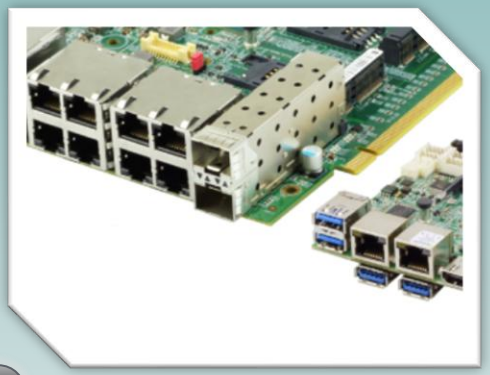
DIP

Dual In-line Package

ISO9001, ISO14001 Certificated

LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Femto-ITX 1.8" :
- 3.5"SBC :
- Computer On Module :
- UPS board :
- Pico-ITX 2.5" :
- 5 ¼" （200 x 150mm）:
- CPU board :

2 Customized Motherboard & Chassis

Innovating Research & Integration Services for Global OEM/ODM and System Integrators

• Applications

Smart Manufacturing / Machine Vision

AI / Visual Analytics

IoT / IIoT

Smart Healthcare/ AI Medical Imaging

Smart Transportation & Railways

Maritime Shipping & Navigation

Networking/ Communication Equipment

Edge Computing Edge Gateway Control

Defense / Military Robust Computers

LEX SYSTEM – Embedded Solution

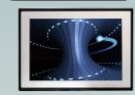
3 Fanless Rugged Panel PC, Fanless Embedded Systems, Servers

4 Expansion Boards/Cards & Related Accessories

Fanless Rugged Panel PC

•SUPER **series** (7”/10.1”/10.4”/15”)

•VITA **series** (10.1”/15”/21.5”/23.8”)



•Slim series (8.4”/10.2”/15.1”/17”)

•SHARK IP66/67 **waterproof** (10.1”/13.3”)

•STAR IP66/67 **waterproof** (10.4”/12.1”15.1”)

•**Stainless** IP66/IP67/IP69K **waterproof** (10.4”/15.1”/19”)

Fanless Embedded System

•Rugged /Waterproof System

•In-vehicle System

•DIN Rail System

•1U server

•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Car

•USB / SIM / COM / Display Conversion Card

• M.2 / eIO Expansion Card

•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Features & Advantages

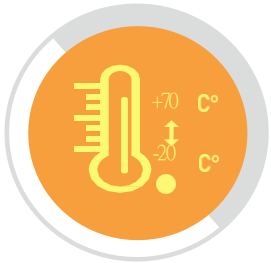
LEX SYSTEM's advantage lies in its flexible integration of custom designs and manufacturing, from motherboards and expansion cards to full systems. This flexibility allows LEX SYSTEM to meet diverse customer needs with tailored solutions in embedded computing, Industry 4.0, digital surveillance, mobile medical devices, smart manufacturing, network applications, machine vision, IoT, big data, and AI platforms.

Flexible

Diverse Expansion interfaces and modules for various Vertical Applications

Integration

Accelerating Customer Development Speed for Cross-Platform products



Stable

Wide Temperature, Wide Voltage & Shock Resistance, IP66/IP67 & IP69K Waterproof Design

Innovation

Fanless small Form Factor Embedded tailored products or space-constrained solutions

Future Development

Scaling Intelligence from Edge to Mission-Critical Environments

Built for extreme conditions, LEX SYSTEM's Edge AI platforms support modern defense, transportation, and industrial automation needs. Featuring waterproof protection, wide-range power input with power on/off ignition delay, wide-temperature endurance, vibration resistance, and flexible customization, our solutions deliver reliable performance for next-generation intelligent systems across global markets.

Highlights Product

Intel® Core™ Ultra (Arrow Lake –S) processors

CI870CW - EVT

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 64GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x eDP / LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

TWISTER(L)-CI870AW

TWISTER(L)-CI870CW

CI870AW - EVT

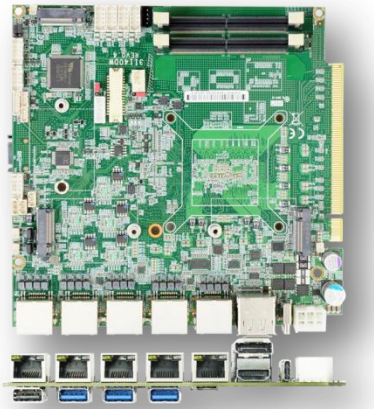
Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 64GB
Multiple Independent display:
1 x HDMI®, 1 x DP,1 x Type C
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

1U Fanless-CI870AW

1U Fanless-CI870CW

Embedded Edge AI Computing

Intel® Core™ Ultra (Meteor Lake-U/H & Arrow Lake-U/H) processors



3I140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, 1 x DP, LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 2 x CANBus 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+9~36V
Dimension: 150 x 155 mm

HAWK 3I140DW

3I140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, LVDS, 1 x Type C
3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)
4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C,
Wide Range DC IN+9~36V
Dimension: 146 x 150 mm

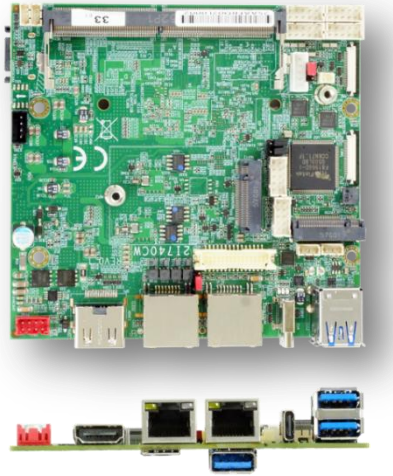
SealPro 3I140HW

Intel® ATOM™ (Amston Lake) processors

2I740DW

Intel® ATOM Amston Lake x7211/x7213 CPU
Onboard LPDDR5, 8GB / 16GB
HDMI® , 3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x COM,
2 x USB 2.0, 2 x M.2 ,1 x Nano SIM, DC-IN 9~/24
115.4 x 84.5 mm

Ultra Compact Fanless System:
NET-II 2I740DW



2I740CW

Intel® ATOM Amston Lake x7211/x7213 CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C , 2 x MIPI-CSI, 4DI/4DO
2 x M.2 , 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm

13th Gen Intel Raptor Lake Core™ Solution

2I130DW

2I130HW

SKY 2 2I130DW

ROCK 2 2I130DW

Fox 2I130DW

ROCK 2I130HW

SealPro 2I130HW

3I130DW

3I130TW

HAWK 3I130DW

SKY 3 3I130DW

HWAK 3I130TW

High Performance Computing

Compact ARM-based Edge AI

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON Orin™ NX | JETSON Orin™ Nano | NVIDIA

CPU Board:
NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs
NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs
AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key, URAT, I2S, 2 x I2C

FOX 2NOR02

2NOR03

1 x HDMI ®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**

FOX 2NOR03+GM04

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I²S, 3 x I²C,8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control

HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR01

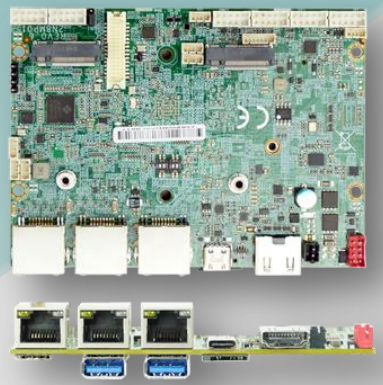
1 x HDMI®, , 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0

SKY 2 2NOR01

Rock 2NOR01

Compact ARM-based Edge AI

NXP i.MX8M Plus /ARM Cortex-A53 CPU



2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO,1 x MIPI (CSI),1 x CANBus

NET-II 2N8MP01

EMPOWERED BY HAILO

MINI -NXPHAI02

Compact Edge AI Box with Hailo-8™ AI processor

NXP-HAI02

NXP-HAI03

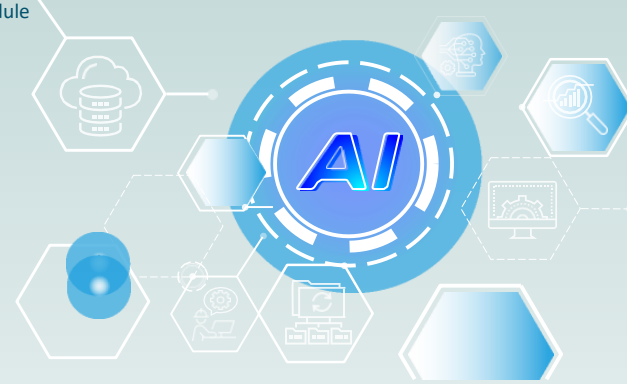
NXP-HAI02 Back
With NEX-8MP computer on module

MINI -NXPHAI02

MINI -NXPHAI03

PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI®; 2 x GbE ; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V



Edge AI Embedded System

Smart Manufacturing

HAILO-AI AI Computing Chipset

SKY 2 2I640HL on board Hailo-8 Edge AI processor

- Machine Vision
- Smart City
- Smart Healthcare
- Smart Transportation
- Smart Retail
- Intelligent Manufacturing
- Automated Factories
- Industry 4.0
- Networking Applications
- Digital Monitoring
- Internet of Things (IoT)

Contact Us

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